

Electrical Performance

Parameter	Min.	Typ.	Max.	Units	Notes
Output frequency	1.8432		80	MHz	As specified
Supply voltage	+2.375	+2.5	+2.625	V	
Supply current, output enabled			8	mA	1.8432 to 50 MHz
			18		>50 MHz
Supply current, standby mode			10	μA	Output Hi-Z
Frequency stability			±25 to ±50	ppM	See Note 1 below
Operating temperature	-40		+85	°C	As specified
Output logic 0, VOL			10% V _{DD}	V	I _{OL} = 4mA min
Output logic 1, VOH	90% V _{DD}			V	I _{OH} = -4mA max
Output load			15	pF	
Duty cycle	45		55	%	-40 to +85°C measured 50%VDD
Rise and fall time			5	ns	measured 10/90% of waveform
Jitter, Phase	up to 75 MHz		1.5	ps RMS (1-σ)	10kHz to 20 MHz frequency band
	75 to 100 MHz		1		
Jitter, Accumulated	up to <75 MHz		5	ps RMS (1-σ)	20.000 adjacent periods
	75 to 100 MHz		3		
Jitter, Total	up to <75 MHz		50	ps pk-pk	100.000 random periods
	75 to 100 MHz		30		

Notes:

- As specified. Stability includes all combinations of operating temperature, load changes, rated input (supply) voltage changes, initial calibration tolerance (25°C), aging (1 year at 25°C average effective ambient temperature), shock and vibration.
- Note: For specifications other than those listed, please contact sales.

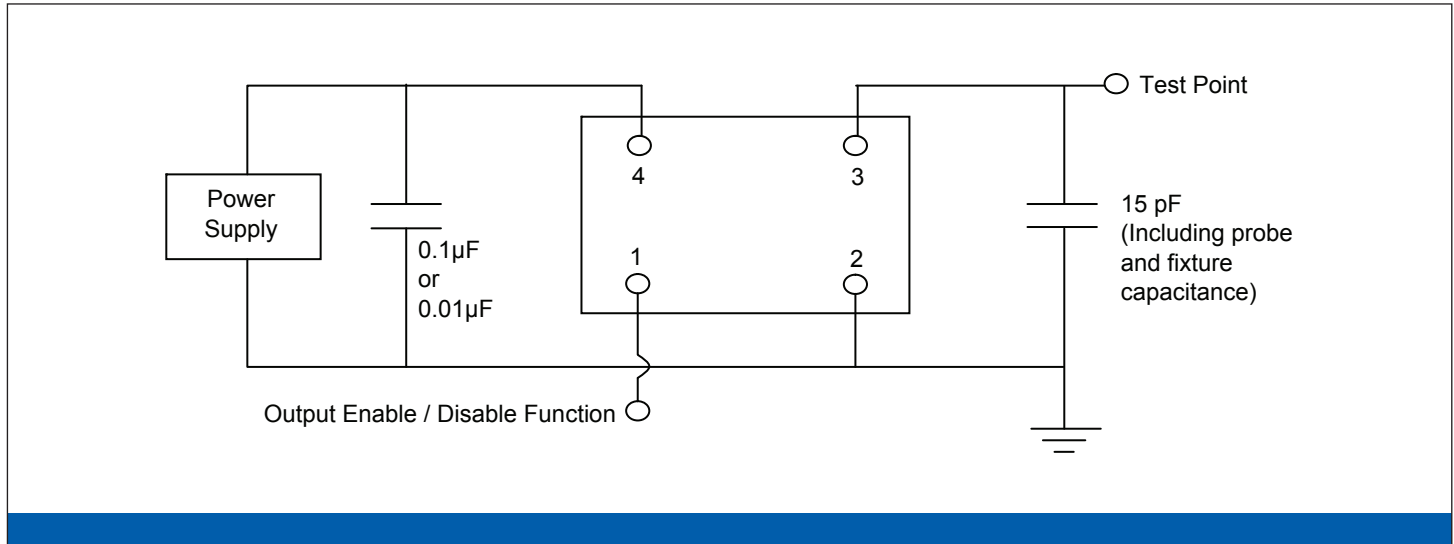
Output Enable / Disable Function

Parameter	Min.	Typ.	Max.	Units	Notes
Input Voltage (pin 1), Output Enable	0.7V _{DD}			V	or open
Input voltage (pin 1), Output Disable (low power standby)			0.3V _{DD}	V	Output is Hi-Z
Internal pullup resistance	50			kΩ	
Output disable delay			100	ns	
Output enable delay			10	ms	

Absolute Maximum Ratings

Parameter	Min.	Typ.	Max.	Units	Notes
Storage temperature	-55		+125	°C	

Test Circuit

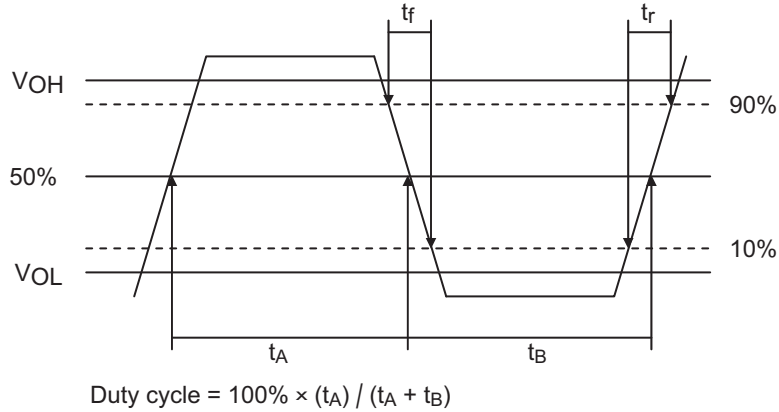


Reliability Test Ratings

This product is rated to meet the following test conditions:

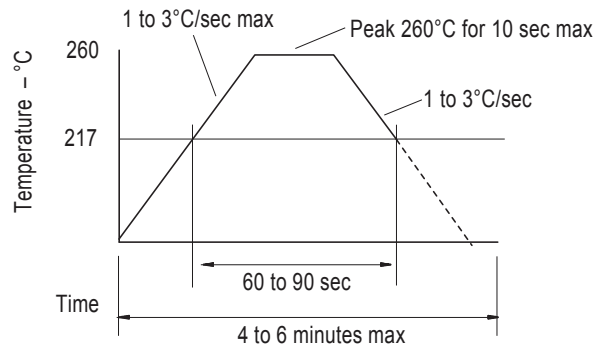
Type	Parameter	Test Condition
Mechanical	Shock	MIL-STD-883, Method 2002, Condition B
Mechanical	Solderability	JESD22-B102-D Method 2 (Preconditioning E)
Mechanical	Terminal strength	MIL-STD-883, Method 2004, Condition D
Mechanical	Gross leak	MIL-STD-883, Method 1014, Condition C
Mechanical	Fine leak	MIL-STD-883, Method 1014, Condition A2 ($R_1 = 2 \times 10^{-8}$ atm cc/s)
Mechanical	Solvent resistance	MIL-STD-202, Method 215
Environmental	Thermal shock	MIL-STD-883, Method 1011, Condition A
Environmental	Moisture resistance	MIL-STD-883, Method 1004
Environmental	Vibration	MIL-STD-883, Method 2007, Condition A
Environmental	Resistance to soldering heat	J-STD-020C Table 5-2 Pb-free devices (2 cycles max)

Output Waveform

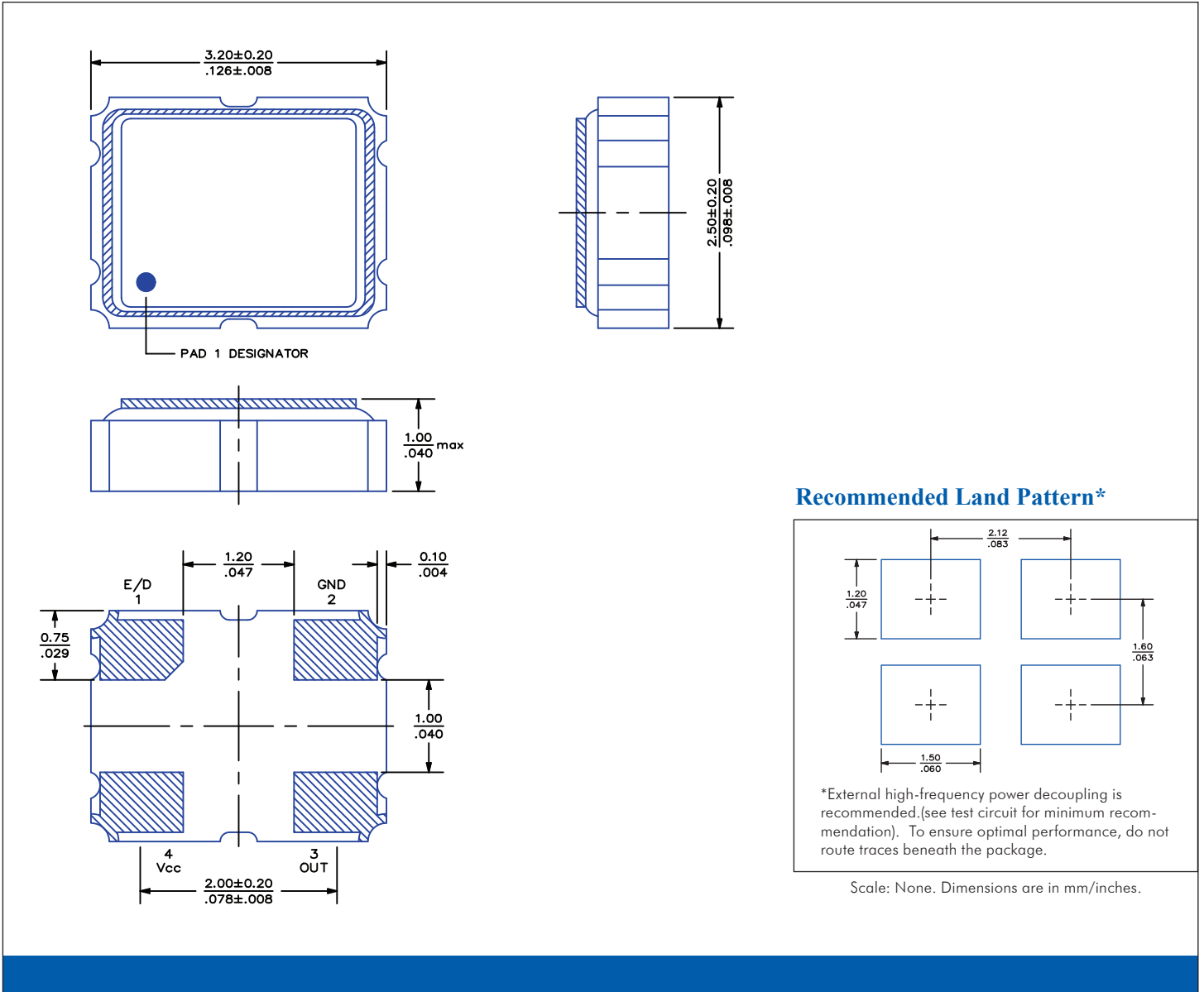


Reflow Soldering Profile

As per IPC/JEDEC J-STD-020C



Mechanical Drawings



Mouser Electronics

Authorized Distributor

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